

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"6337030".PN.	USPAT; USOCR	OR	OFF	2005/03/18 10:47
L2	0	"6187216".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 10:48
L4	166	ultrasonic\$4 same etch\$4 same (tank or vessel or bath) same heat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:01
L5	1608367	"14" and heat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:01
L6	868	ultrasonic\$4 same etch\$4 same (tank or vessel or bath)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:22
L7	559	6 and heat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:02
L8	265	7 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:23
L9	190	ultrasonic\$4 same etch\$4 same tanks	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:09
L10	19	ultrasonic\$4 and etch\$4 and (inner adj tank)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:18
L11	5849	ultrasonic\$4 and etch\$4 and (tank or vessel or bath) and heat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:23

L12	2978	ultrasonic\$4 and etch\$4 and (tank or vessel or bath) and heat\$4 and (lid or cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:23
L13	1588	12 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:25
L14	137	13 and "134"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:25

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L14	137	13 and "134"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/18 11:25